

General Description

The 20N06 combines advanced trench MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance.

These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 20A, 60V. $R_{DS(ON)} = 0.046\Omega @ V_{GS} = 10V$
- Fast switching
- Low Threshold Drive

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current	20	A
$I_D @ T_A = 100^\circ C$	Continuous Drain Current	10	A
I_{DM}	Pulsed Drain Current	60	A
EAS	Single Pulse Avalanche Energy (Note 1)	170	mJ
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	60	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Note 2)	---	80	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	2.5	$^\circ C/W$

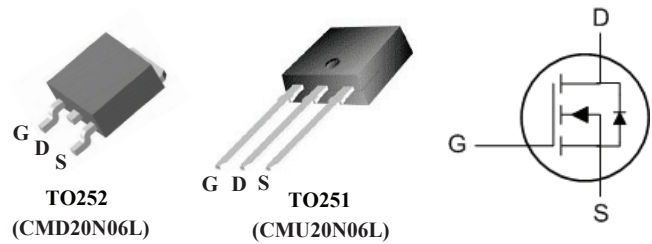
Product Summary

BVDSS	RDSON	ID
60V	46m Ω	20A

Applications

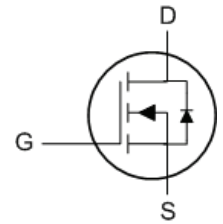
- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

TO252 / TO251 Pin Configuration



TO252
(CMD20N06L)

TO251
(CMU20N06L)



Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$, $I_D=250\mu A$	---	0.07	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=10A$ (Note 3)	---	---	46	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1	---	3	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V$	---	---	1	μA
		$V_{DS}=60V, V_{GS}=0V, T_J=150\text{ }^\circ\text{C}$	---	---	10	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=7V, I_D=6A$	---	13	---	ms
Q_g	Total Gate Charge	$V_{DS}=48V, V_{GS}=10V, I_D=20A$ (Note 3)	---	21	---	nC
Q_{gs}	Gate-Source Charge		---	5.6	---	
Q_{gd}	Gate-Drain Charge		---	7.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=9.1\Omega$ $I_D=20A$ (Note 3)	---	10	---	ns
T_r	Rise Time		---	62	---	
$T_{d(off)}$	Turn-Off Delay Time		---	27	---	
T_f	Fall Time		---	40	---	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	720	---	pF
C_{oss}	Output Capacitance		---	205	---	
C_{rss}	Reverse Transfer Capacitance		---	48	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	20	A
I_{SM}	Pulsed Source Current		---	---	60	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=20A$ (Note 3)	---	---	1.2	V

Notes :

1. $V_{DD} = 25V, V_{GS} = 10V, L = 1.0\text{ mH}, I_L(pk) = 18.4\text{ A}, V_{DS} = 60V$, Starting $T_J = 25\text{ }^\circ\text{C}$.
2. When surface mounted to an FR4 board using the minimum recommended pad size.
3. Pulse Test: Pulse Width $\leq 300\text{ }\mu s$, Duty Cycle $\leq 2\%$.